

## 30V Dual P-Channel Enhancement Mode MOSFET

### Description

The N4953C uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a load switch or in PWM applications.

### General Features

- ◆  $V_{DS} = -30V$ ,  $I_D = -5.5A$   
 $R_{DS(ON)}(Typ.) = 55m\Omega$  @  $V_{GS} = -4.5V$   
 $R_{DS(ON)}(Typ.) = 45m\Omega$  @  $V_{GS} = -10V$
- ◆ High power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

### Application

- ◆ PWM applications
- ◆ Load switch

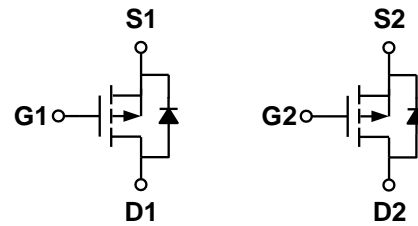
*100% UIS TESTED!*  
*100%  $\Delta V_{ds}$  TESTED!*

### Package

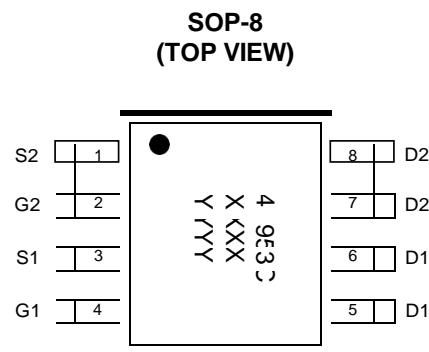
- ◆ SOP-8



### Schematic diagram



### Marking and pin assignment



Note: XXXX is the date code, YYYY is the Quality Code

### Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
PECN4953CS R-G	-55°C to +150°C	SOP-8	4000

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	-30	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous (Silicon Limited)	$I_D$	$T_A = 25^\circ C$	-5.5
		$T_A = 75^\circ C$	-4
Pulsed Drain Current (Package Limited)	$I_{DM}$	-22	A
Maximum power dissipation	$P_D$	$T_A = 25^\circ C$	3.0
		$T_A = 75^\circ C$	2.1
Operating junction Temperature range	$T_j$	-55—150	°C

## Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-body leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
<b>ON Characteristics</b>						
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.7	-1.3	-2.0	V
Drain-source on-state resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-5.5A$	-	45	65	m $\Omega$
		$V_{GS}=-4.5V, I_D=-4.5A$	-	55	90	
Forward transconductance	$g_{fs}$	$V_{GS}=-5V, I_D=-5A$	-	5	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{ISS}$	$V_{DS}=-15V, V_{GS}=0V$ $f=1.0MHz$	-	700	-	pF
Output capacitance	$C_{OSS}$		-	120	-	
Reverse transfer capacitance	$C_{RSS}$		-	70	-	
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{D(ON)}$	$V_{DD}=-15V$ $I_D=-5.5A$ $V_{GEN}=-10V$ $R_L=10\Omega$ $R_{GEN}=6\Omega$	-	9	-	ns
Rise time	$t_r$		-	5	-	
Turn-off delay time	$t_{D(OFF)}$		-	28	-	
Fall time	$t_f$		-	12.5	-	
Total gate charge	$Q_g$	$V_{DS}=-15V, I_D=-5.5A$ $V_{GS}=-10V$	-	14	-	nC
Gate-source charge	$Q_{gs}$		-	3.1	-	
Gate-drain charge	$Q_{gd}$		-	3	-	

## Thermal Characteristics

Parameter		Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient <sup>A</sup>	$\leq 10s$	$R_{\theta JA}$	33	40	$^{\circ}C/W$
Maximum Junction-to-Ambient <sup>A</sup>	Steady-State		59	75	
Maximum Junction-to-Lead <sup>B</sup>	Steady-State	$R_{\theta JC}$	16	24	

A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}C$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10s$  thermal resistance rating.

B: The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JC}$  and lead to ambient.

## Typical Performance Characteristics

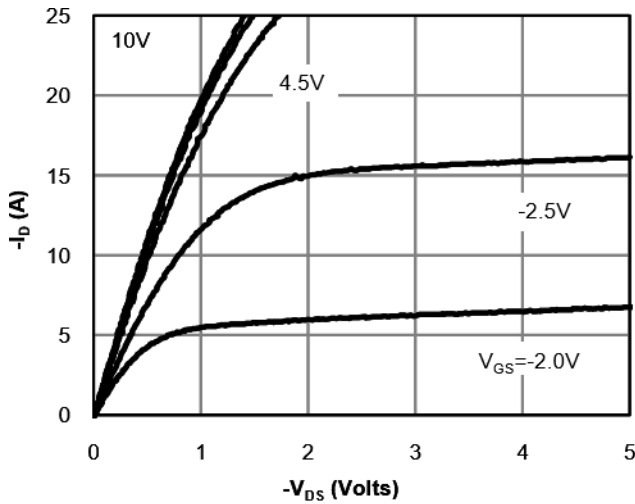


Fig 1: On-Region Characteristics (Note E)

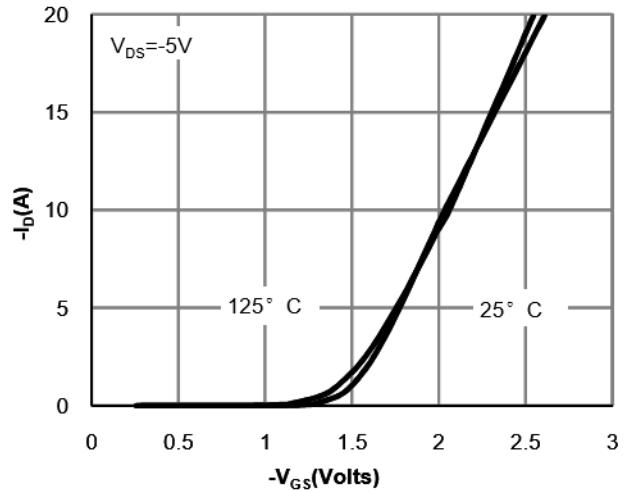


Figure 2: Transfer Characteristics (Note E)

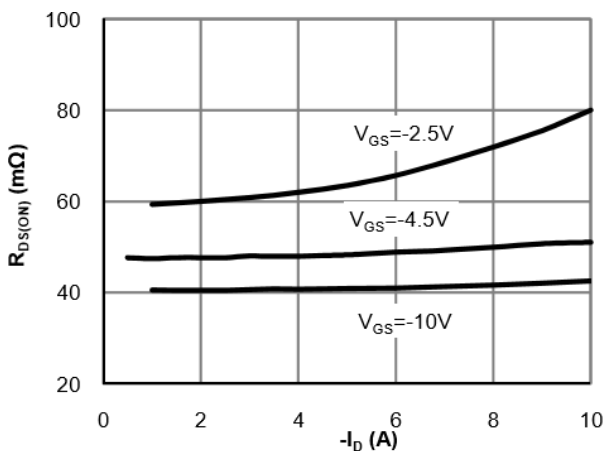


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

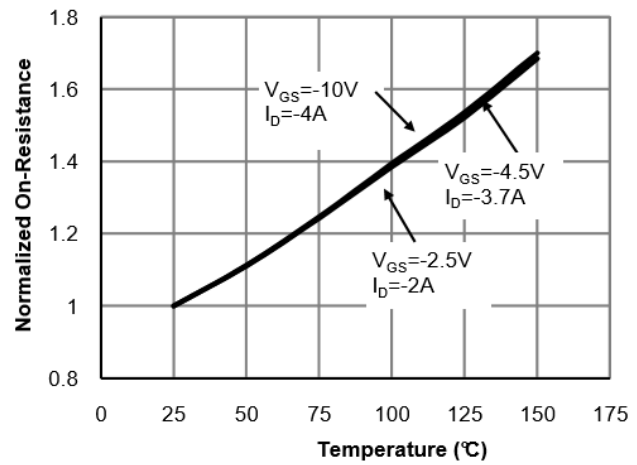


Figure 4: On-Resistance vs. Junction Temperature (Note E)

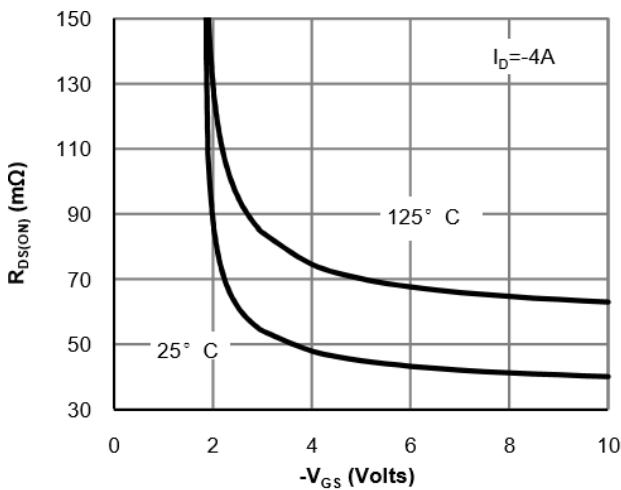


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

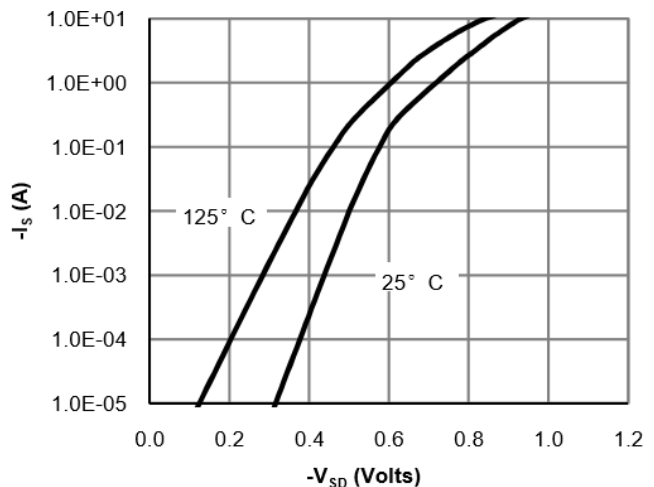


Figure 6: Body-Diode Characteristics (Note E)

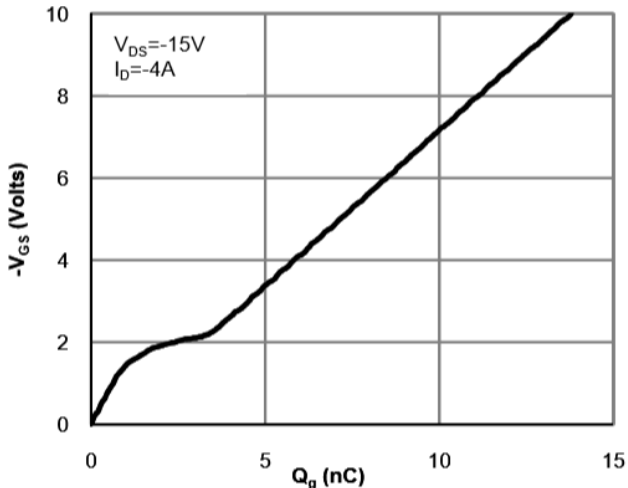


Figure 7: Gate-Charge Characteristics

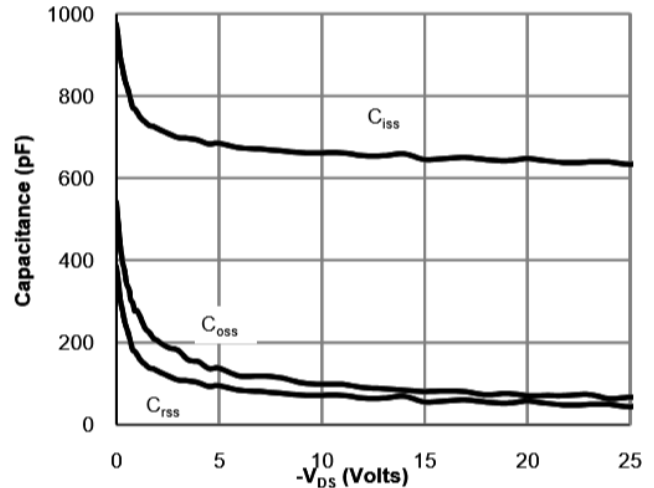


Figure 8: Capacitance Characteristics

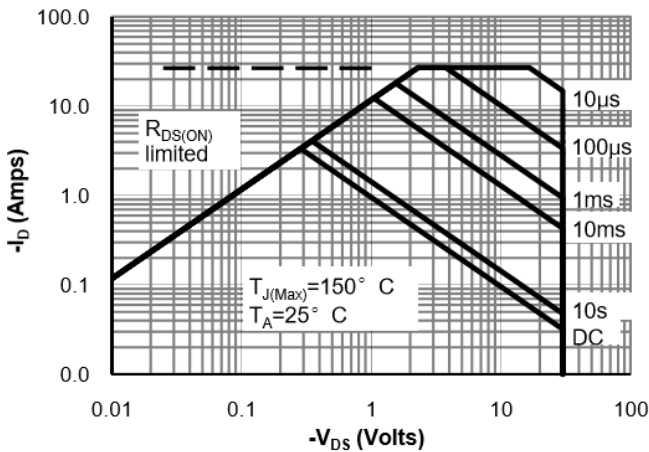


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

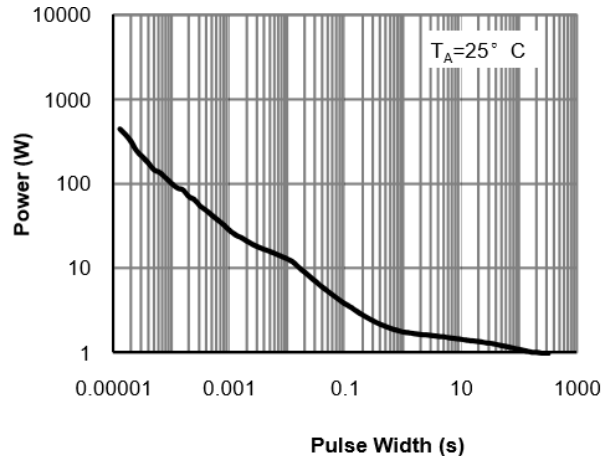


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

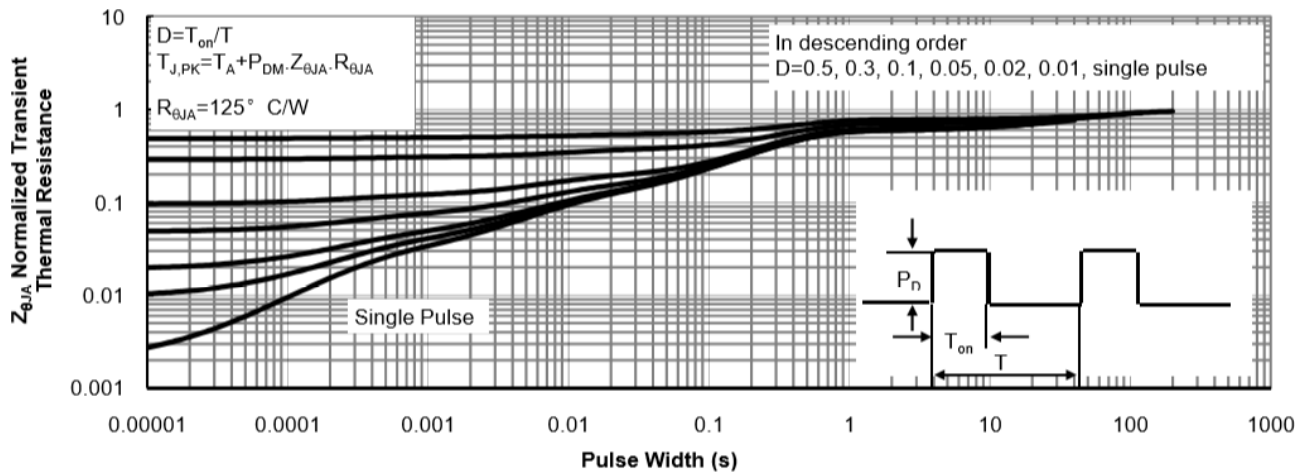
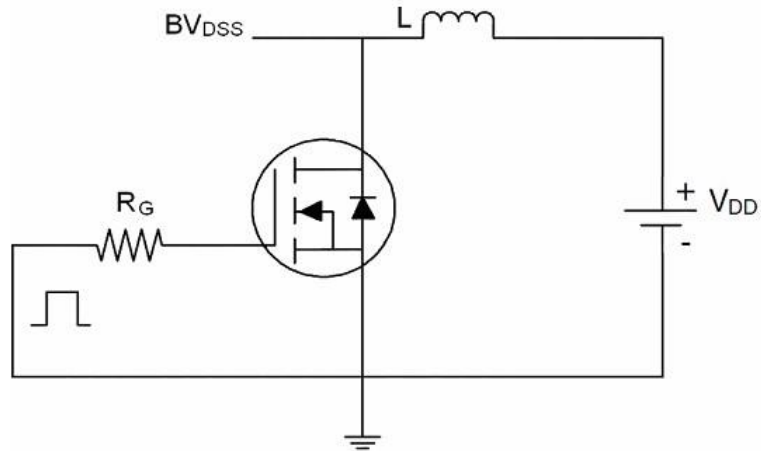


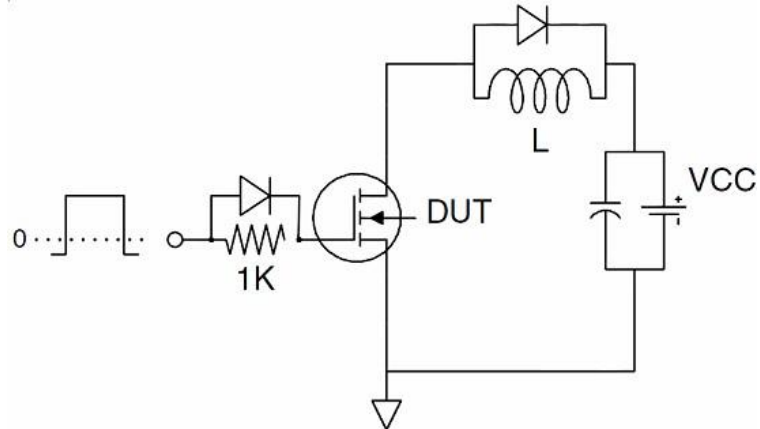
Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

## Test Circuit:

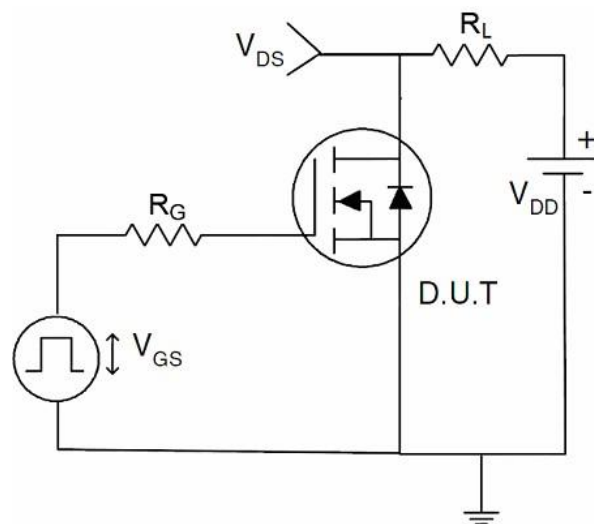
1 、 EAS Test Circuit



2 、 Gate Charge Test Circuit

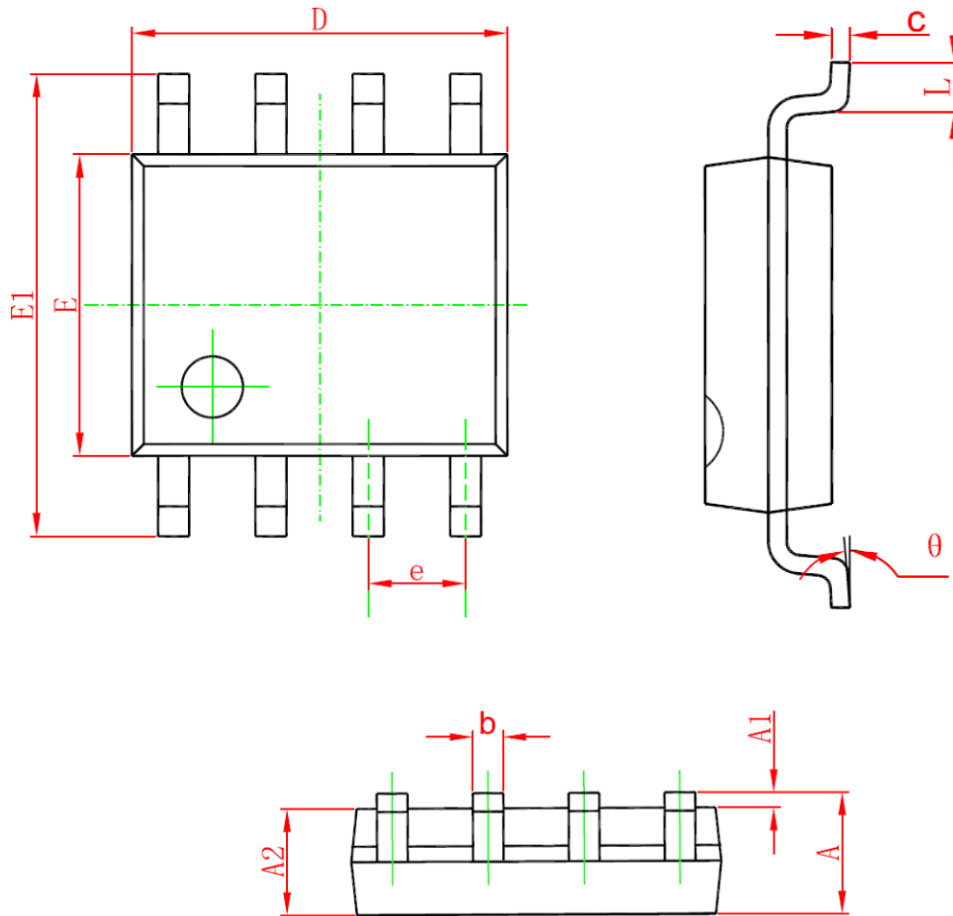


3 、 Switch Time Test Circuit



## Package Information

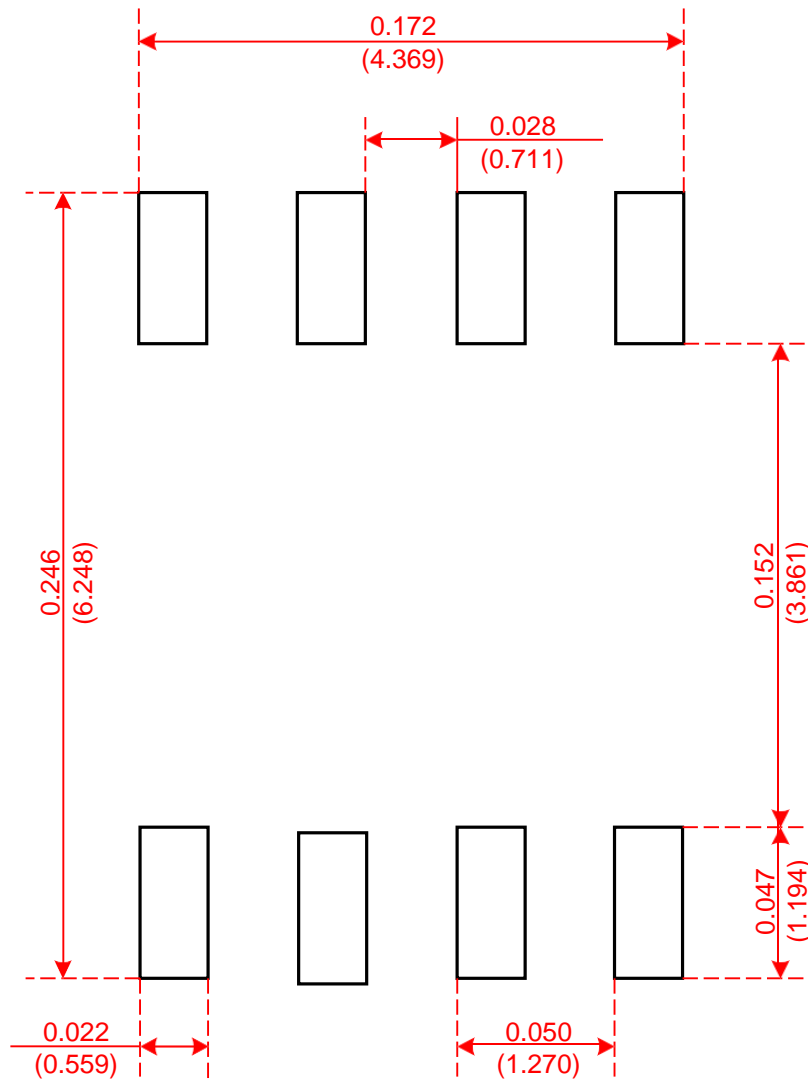
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Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

## Recommended Minimum Pads

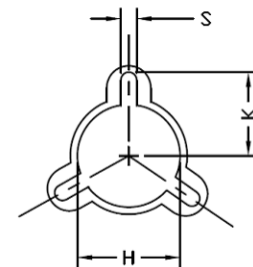
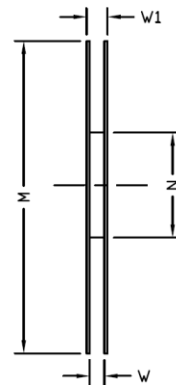
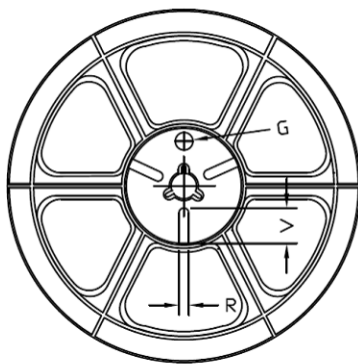
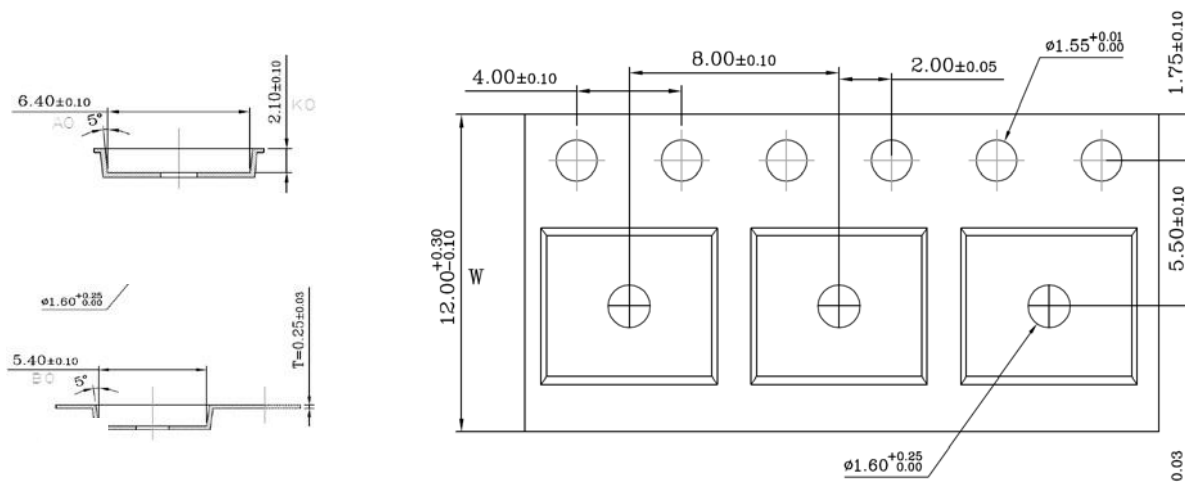
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Recommended Minimum Pads  
Dimensions in Inches/(mm)

## Tape and Reel

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Tape Size	Reel Size	M	N	W	W1	H	K	S	G	R	V
12mm	Φ330	Φ330.00 ±0.50	Φ97.00 ±0.30	13.00 ±0.30	17.40 ±1.00	Φ13.00 ±0.5	10.6	2.00 ±0.50	—	—	—

Unit Per Reel:  
4000pcs

